

**ABSTRACT OF THE DISCLOSURE**

In an electronic apparatus, having a heat diffusion structure having high efficiency, for corresponding to small-sizing and high-performances of an electronic part therein, a liquid sealing portion is provide on a cover on a side of the electronic part, which builds up a water-cooling jacket attached on an upper portion of the electronic part. Further, within an inside of this liquid sealing portion, a heat diffusion plate is provided, extending from the vicinity of the center of the water-cooling jacket in zigzag manner. With this, heat generated from the electronic part can be spread all over the cover, as a whole, on the side of the electronic part, with an aid of the evaporation heat of the liquid. The heat spread can be transmitted into the cooling liquid circulating within a housing thereof, through liquid flow passages of the water-cooling jacket, thereby being radiated into the atmosphere from the portion having a large or wide heat radiation area of the housing. Further, the heat generated from the electronic parts can be further spread, up to the water-cooling jacket having a wide area.